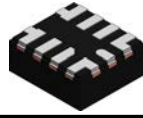


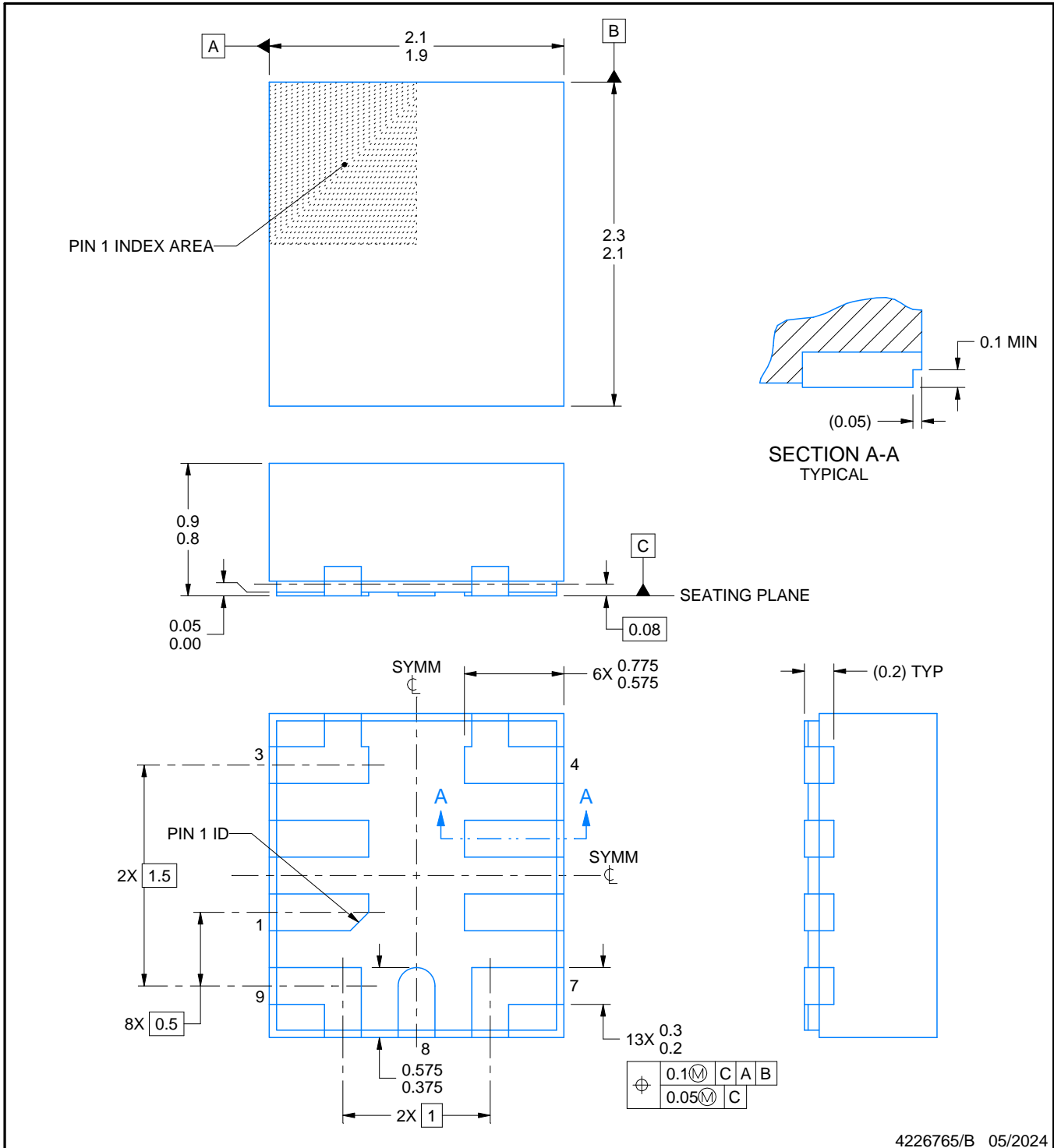
RYT0009A



PACKAGE OUTLINE

VQFN-HR - 0.9 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4226765/B 05/2024

NOTES:

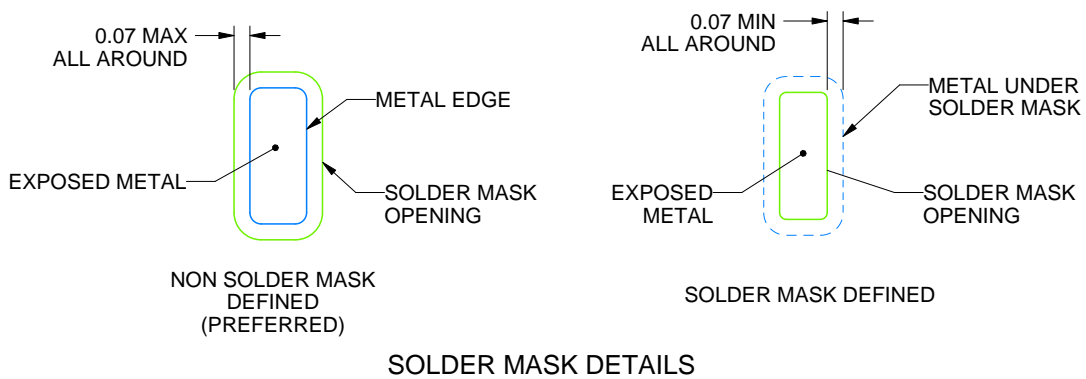
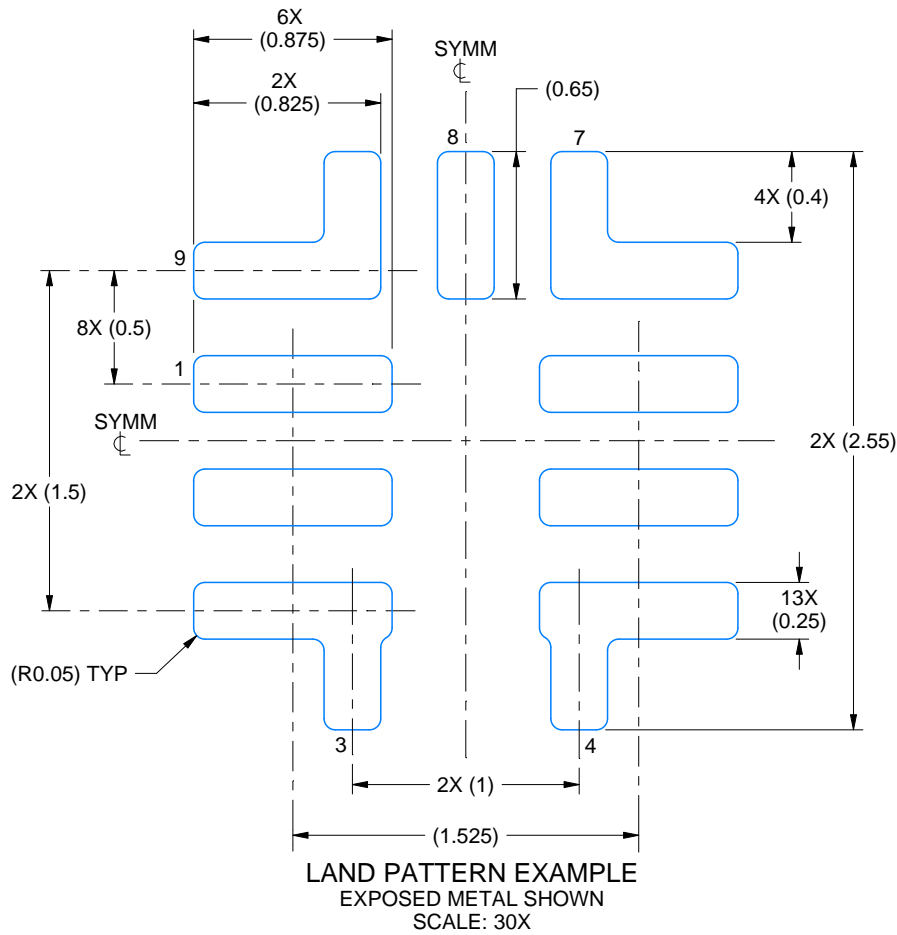
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

RYT0009A

VQFN-HR - 0.9 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4226765/B 05/2024

NOTES: (continued)

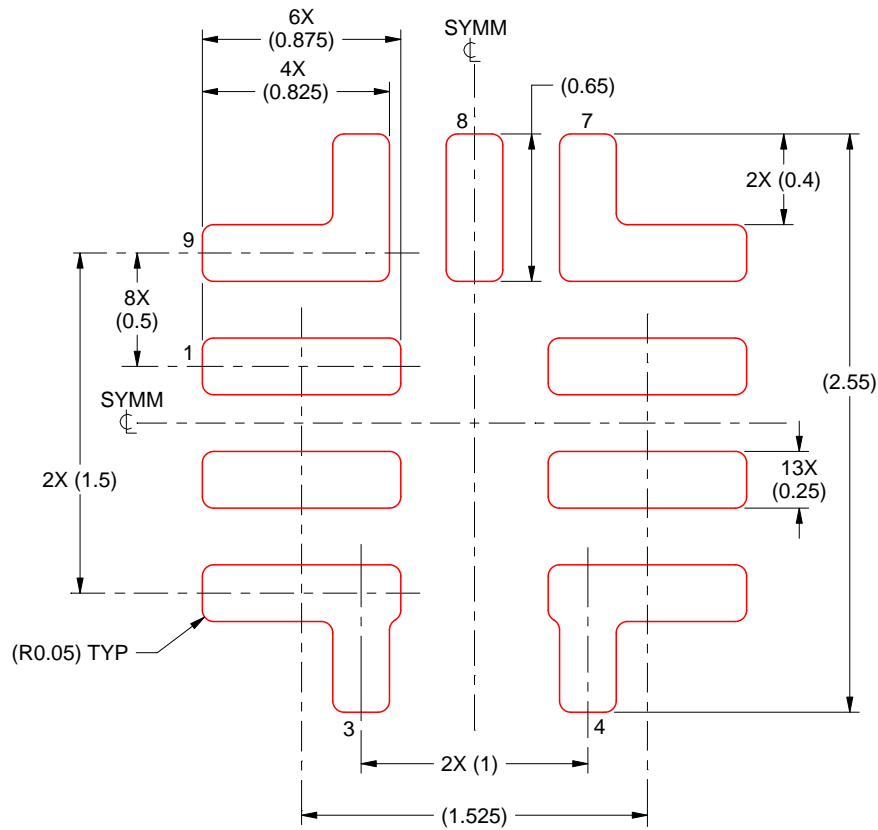
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

RYT0009A

VQFN-HR - 0.9 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 30X

4226765/B 05/2024

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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